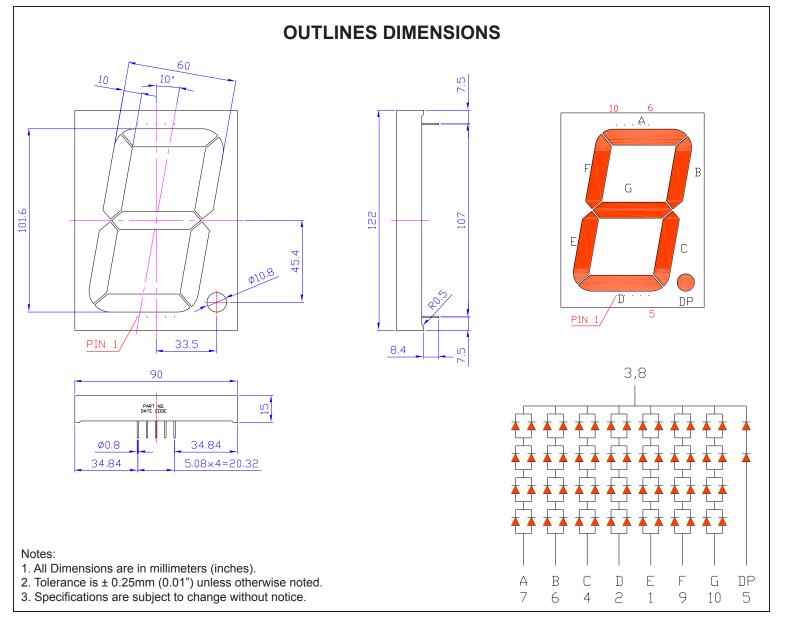


SPECIFICATIONS

CDSC400A2W



Part Number	Chip Material	Color of Emission	Lens Type	Description
CDSC400A2W	InGaAIP	Amber	White Segment	Common Cathode



ChromeLED Corp. reserves the right to make changes at any time in order to supply the best product possible. The most current version of this document will always be available at: www.chromeled.com



ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit
Power Dissipation	PD	70	mW
Pulse Forward Current	IFP	90	mA
Continuous Forward Current	lf	25	mA
Reverse Voltage	VR	5	V
Operating Temperature Range	Topr	-25~+85	°C
Storage Temperature Range	Тѕтс	-25~+85	°C
IFP = Pulse Width \leq 10 ms, Duty Ratio \leq 1/10. Soldering Condition: 260 °C/ 5sec			

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

Parameter	Symbol	Test Condition	Value			Lipit
			Min	Тур	Max	Unit
Luminous Intensity	lv	l⊧ = 20mA	-	250	-	mcd
Forward Voltage per Segment	VF	l⊧ = 40mA	-	8.2	9.6	V
Reverse Leakage Current	lr	V _R = 20V	-	-	10	μA
Peak Wavelength	λP	l⊧ = 20mA	-	632	-	nm
Dominant Wavelength	λd	l⊧ = 20mA	-	624	-	nm
Spectral Radiation Bandwidth	Δλ	l⊧ = 20mA	-	20	-	nm

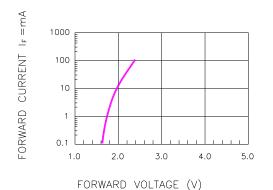


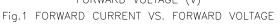
ChromeLED Corp. reserves the right to make changes at any time in order to supply the best product possible. The most current version of this document will always be available at: www.chromeled.com



OPTICAL CHARACTERISTIC CURVES

Typical Electro-optical Characteristic Curves (25 °C Free Air Temperature Unless Otherwise Specified)





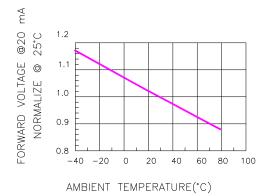
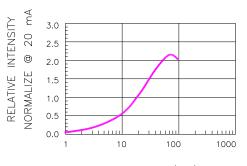


Fig.3 FORWARD VOLTAGE VS. TEMPERATURE



FORWARD CURRENT (mA) Fig.2 RELATIVE INTENSITY VS. FORWARD CURRENT

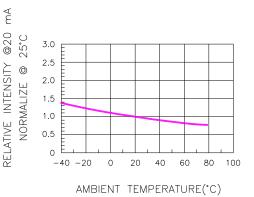
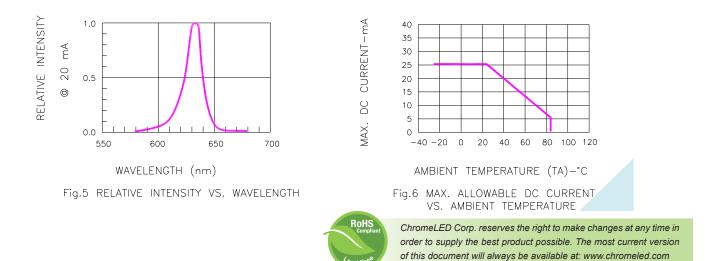


Fig.4 RELATIVE INTENSITY VS. TEMPERATURE



17800 Castleton Street, #388 | City of Industry, CA 91748 | T: 626-964-9040 | F: 626-964-9072 | www.chromeled.com



SOLDERING CONDITIONS – LAMP TYPE LED

- * Solder the LED no closer than 3mm from the base of the epoxy bulb. Soldering beyond the base of the tie bar is recommended.
- * Recommended soldering conditions

Dip Soldering			
Pre-Heat	100 °C Max		
Pre-Heat Time	60 Second Max		
Solder Bath Temperature	260 °C Max		
Dippng Time	5 Second Max		
Dipping Position	No lower than 3mm from the base of the epoxy		

Hand Soldering				
Temperature Soldering Time Position	3mm Series	Others		
	300 °C Max	350 °C Max		
	3 Second Max	3 Second Max		
	No closer than 3mm from the	No closer than 3mm from the		
	base of the epoxy	base of the epoxy		

- * Do not apply any stress to the lead. Particularly when heated.
- * The LED must not be repositioned after soldering.
- * After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- * Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be caused by the PC board warping or from the clinching and cutting of the leadframes. When it is absolutely necessary, the LEDs may be mounted in this fashion, but, the user will assume responsibility for any problems. Direct soldering should only be done after testing has confirmed that no damage, such as wire bond failure or resin deterioration, will occur. LEDs should not be soldered directly to double sided PC boards because the heat will deteriorate the epoxy resin.
- * When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.
- * Cut the LED leadframes at room temperature. Cutting the leadframes at high temperature may cause LED failure.



ChromeLED Corp. reserves the right to make changes at any time in order to supply the best product possible. The most current version of this document will always be available at: www.chromeled.com